

广东星坤科技股份有限公司

日期

文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
Δ*					ANGLAR ±5°
Δx					L ≤ 4 ±0.2
Δx					4 < L ≤ 16 ±0.3
					16 < L ≤ 63 ±0.4
					L > 63 ±0.5
REVISIONS					UNSPECIFIED TOLERANCES
www.helloxkb.com www.helloxkb.cn www.xk-dg.cn					



DSND		SCALE: N/A	MODEL TYPE:
DWN		VIEW:	PART NO.: X1304WWS-52X-LPV10
CHKD		UNIT: mm/in	DWG NO.:
APPD		SIZE: A4	X-X1304WWS-52X-LPV10
XKB INDUSTRIAL PRECISION CO., LIMITED		WEIGHT	SHEET
		1/1	REVISION
			A0

NOTES 注释:

1. MATERIAL材料:

HOUSING外壳: THERMOPLASTIC, HIGH TEMP.,  
UL94V-0;BLACK COLOR

CONTACTS触点: COPPER ALLOY.

PEGS螺钉: COPPER ALLOY.

2. FINISH饰面:

CONTACT触点:SELECTEIVE GOLD PLATING ON CONTACT AREA.  
100μ"MIN. MATTE TIN PLATING ON SOLDER TAILS,  
50μ" MIN. NICKEL UNDERPLATING OVERALL.

PEGS螺钉: 120u" MIN. MATTE-TIN OVER 50u" MIN. NICKEL.

X1304 W V S - 52 X - LP V10

① ② ③ ④ ⑤ ⑥ ⑦ ⑧

① Series Number

② Terminal form: W-Wafer

③ Welding Board Angle : V-Stright Angle 180°

④ Welding Way:S-SMT

⑤ No.of Pins: 52 PIN

⑥ HEIGHT: A 4.0mm;B 5.2mm;C 5.6mm;D 6.8mm;  
E 7.0mm;F 8.0mm;G 9.0mm;H 9.9mm

⑦ Plastic material: LP-LCP UL94V-0

⑧ Contact Plating:V01-Gold Flash  
V10-Gold 10 u"  
V30-Gold 30 u"

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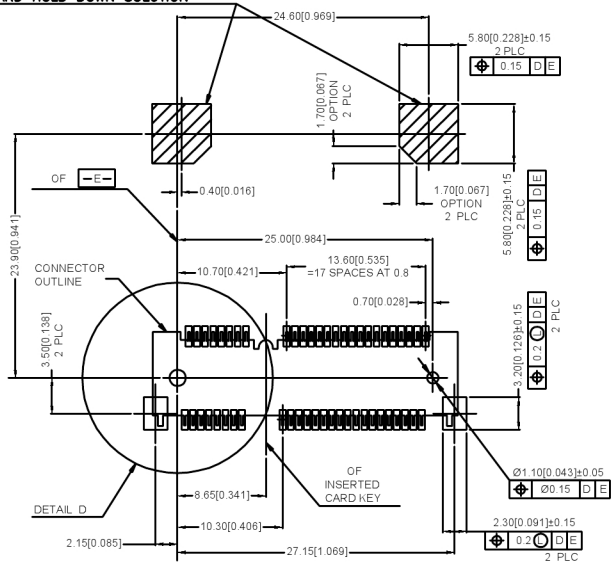
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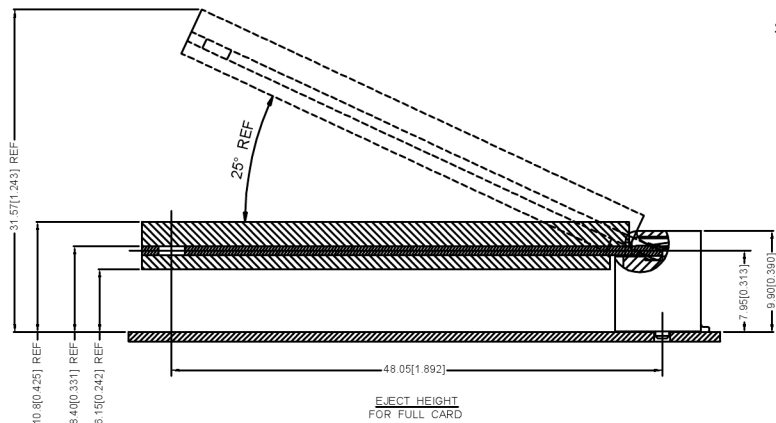
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XKB INDUSTRIAL PRECISION CO.,LIMITED		SHEET 1/1
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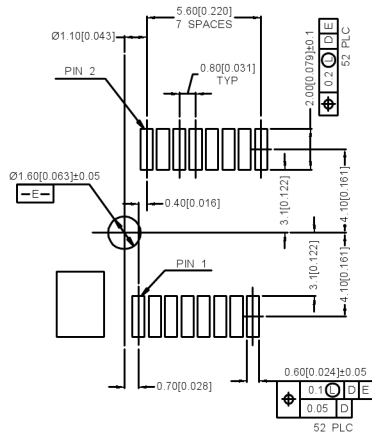
COMPONENT KEEP OUT AREA FOR  
CARD HOLD DOWN SOLUTION



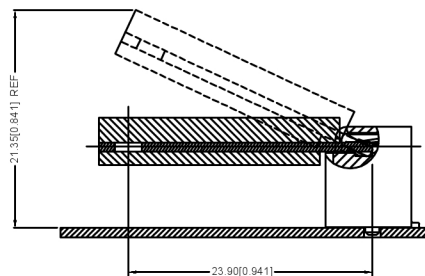
—D— IS THE TOP SURFACE OF PCB.  
RECOMMENDED P.C. BOARD PATTERN LAYOUT  
FOR HALF CARD CONNECTOR  
(TOP VIEW)



EJECT HEIGHT  
FOR FULL CARD

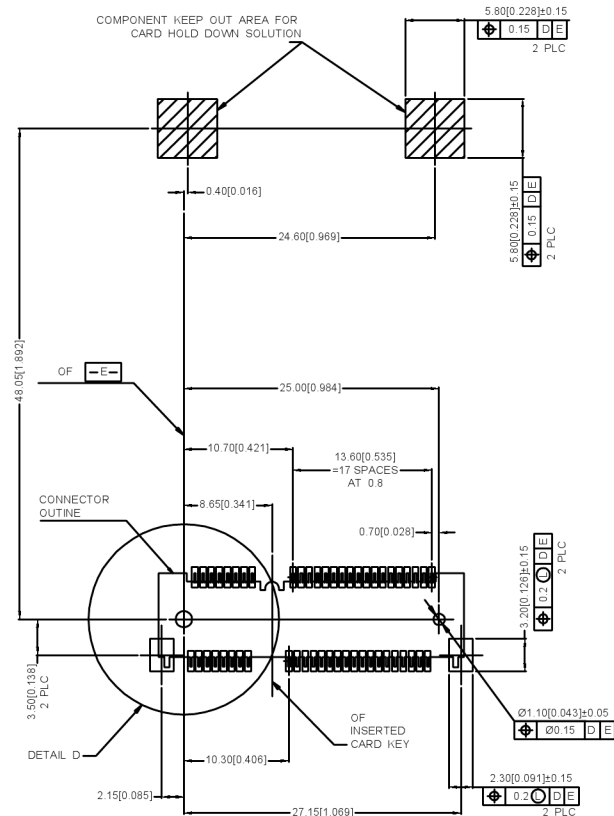


DETAIL D  
SCALE 2:1



EJECT HEIGHT  
FOR HALF CARD

COMPONENT KEEP OUT AREA FOR  
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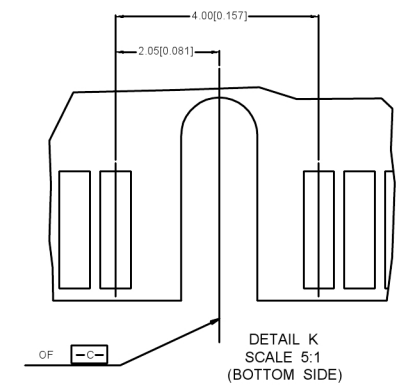
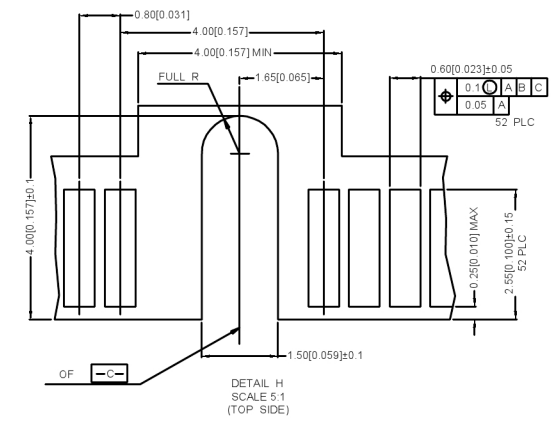
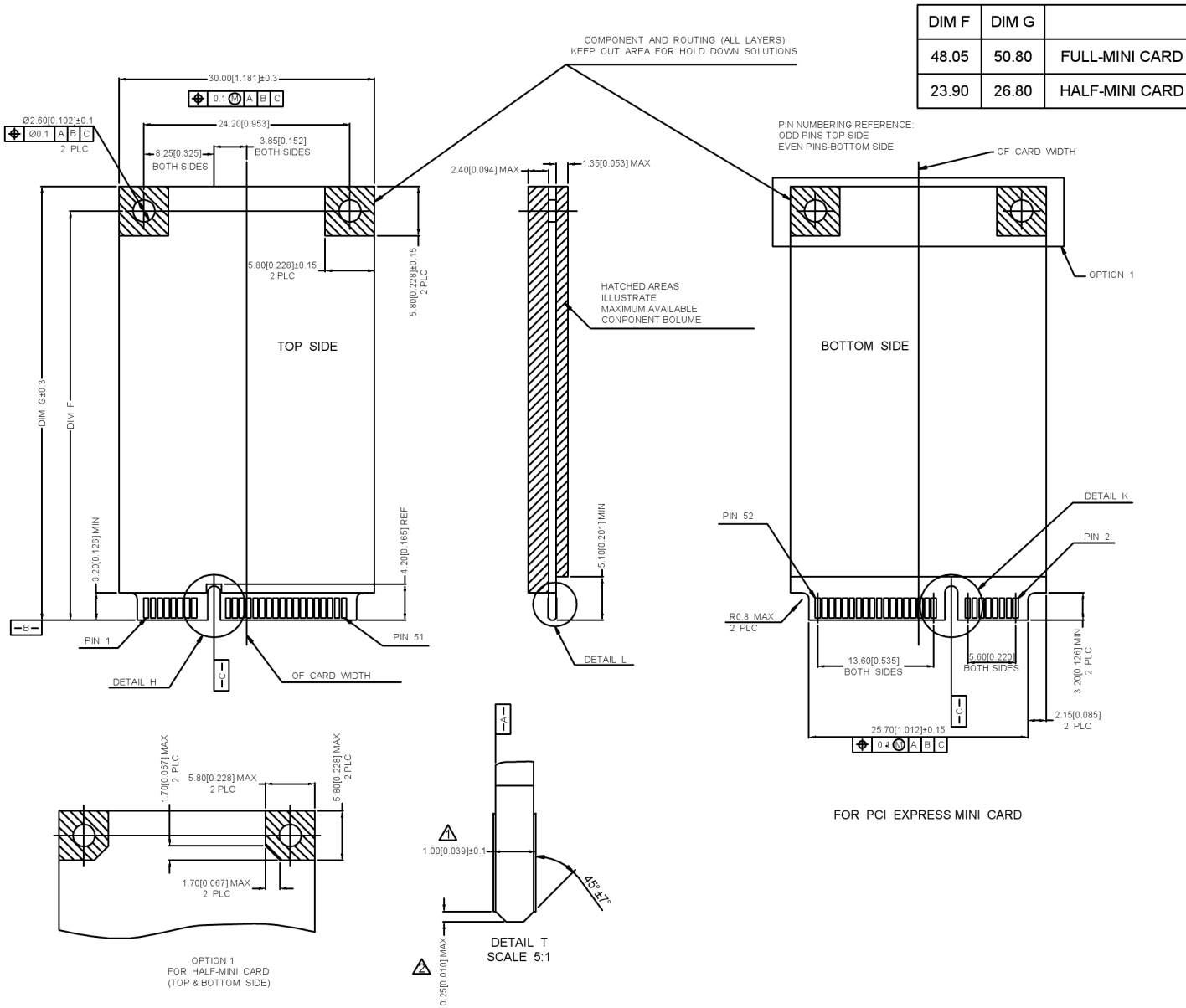
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UNSPECIFIED TOLERANCES							

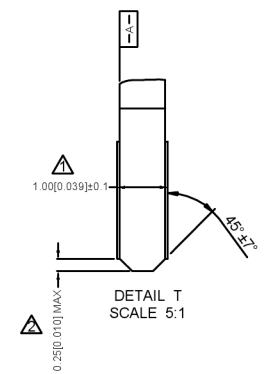
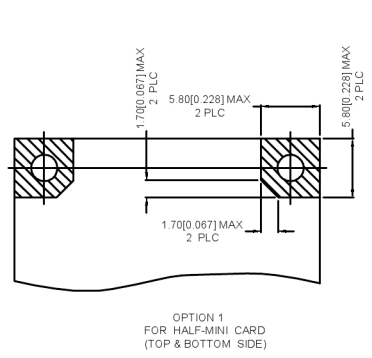


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KKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT
			SHEET
			REVISION
			1/1
			A0



NOTES 注释:

- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.  
卡片厚度适用于所有接线片，包括电镀和/或金属化。
- △ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING CONTACT MATERIALS SURFACES AND PCB BURRS FROM AND PCB  
边缘斜面必须均匀且无切割接触材料毛刺和PCB



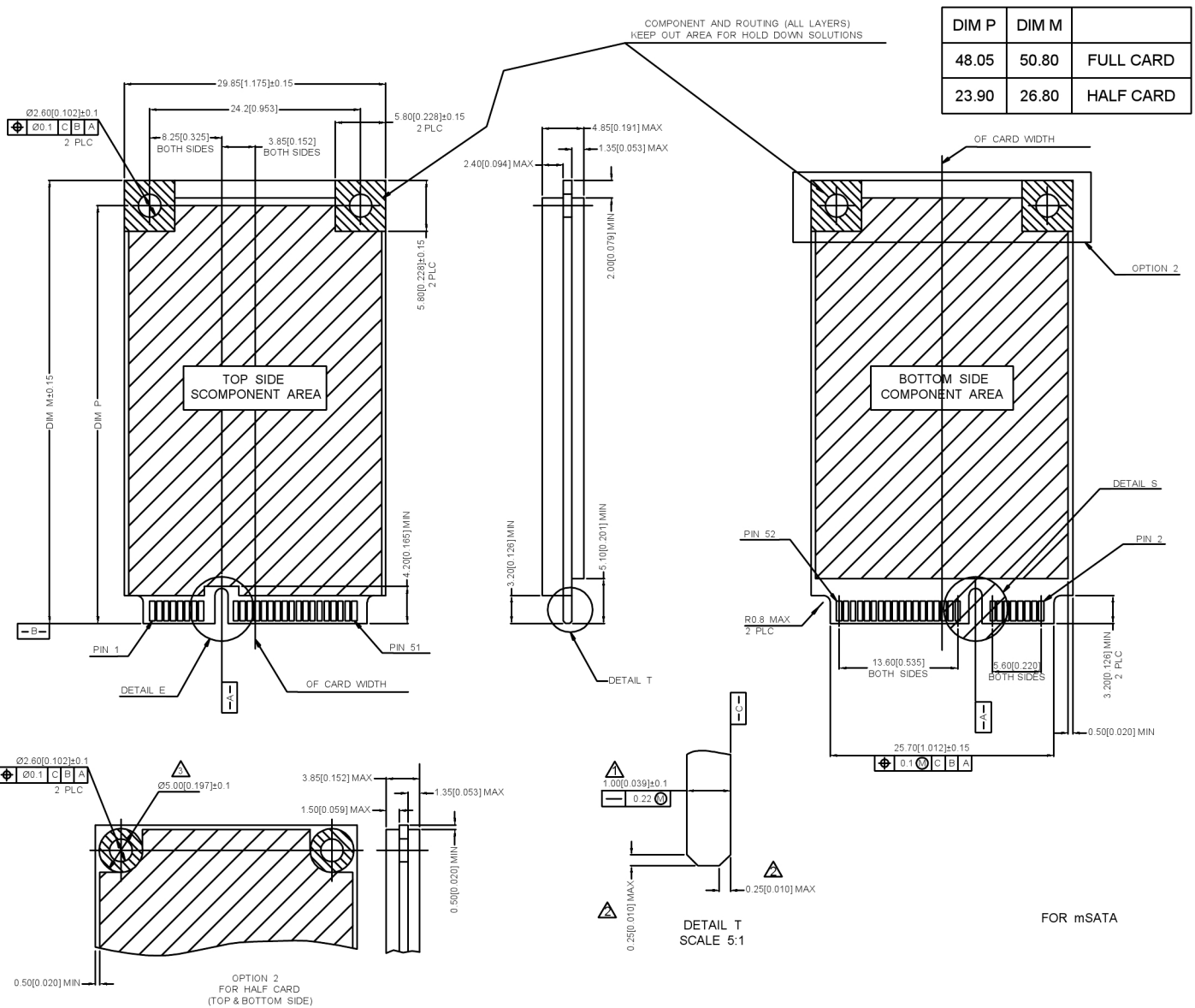
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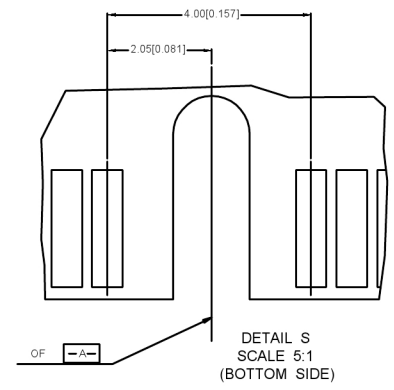
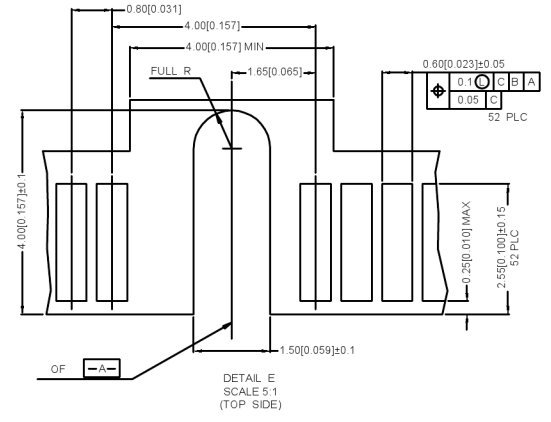
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DIM P	DIM M	
48.05	50.80	FULL CARD
23.90	26.80	HALF CARD



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边缘斜面必须均匀且无切割接触材料毛刺和PCB
  - △ COMPONENT AND ROUTING (TOP/BOTTOM LAYER) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS.  
元件和布线(顶层/底层)为压紧解决方案留出区域

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数量	日期
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